dummy wirings disposed in said at least one of said multilayered wiring layers, outside said signal wiring group, and in parallel to said signal wirings, at least one of said dummy wirings being disposed at each side of said signal wiring group.

Please add new Claims 7-11 as follows:

- 7. (New) The multilayered wiring substrate according to Claim 1, wherein a distance between a dummy wiring adjacent to said signal wirings and said signal wirings is equal to a distance between two adjacent signal wirings of said signal wirings.
- 8. (New) The multilayered wiring substrate according to Claim 1, wherein a distance between any adjacent dummy wirings is equal to a distance between any adjacent signal wirings.
- 9. (New) The multilayered wiring substrate according to Claim 7, wherein a distance between any adjacent dummy wirings is equal to a distance between any adjacent signal wirings.
  - 10. (New) A multilayered wiring substrate, comprising:

a plurality of multilayered wiring layers, at least one of said multilayered wiring layers comprising a signal wiring group made by a plurality of signal wirings disposed in parallel with one another;

through holes formed in a stacking direction of said wiring layers and disposed in each clearance between said signal wirings;

a dummy through hole extending in said stacking direction, disposed outside said signal wiring group; and

conductive layers disposed inside said through holes and said dummy through hole, respectively.